ABSTRACT OF THE DISCLOSURE

A manufacturing apparatus of a semiconductor device includes a stage (12), a bonding head (14), a copying mechanism (22) mounted on the bonding head (14), and a controller (34) executing adjustment processing. In the adjustment processing, the controller (34) causes a facing surface (50) of the bonding head (14) to abut against a reference surface (110) of the stage (12) after setting the copying mechanism (22) to a locked state, then presses the facing surface (50) against the reference surface (110) after switching the copying mechanism (22) to a free state, and after that, switches the copying mechanism (22) to the locked state.

FIG. 7